



## THIS SPEC IS OBSOLETE

Spec No: 001-06517

Spec Title: CY62148BN MOBL(R) 4-MBIT (512K X 8) STATIC RAM

Sunset Owner: Anuj Chakrapani (aju)

Replaced by: NONE

## Features

- 4.5V–5.5V operation
- Low active power
  - Typical active current: 2.5 mA @ f = 1 MHz
  - Typical active current: 12.5 mA @ f = fmax
- Low standby current
- Automatic power down when deselected
- TTL-compatible inputs and outputs
- Easy memory expansion with  $\overline{CE}$  and  $\overline{OE}$  features
- CMOS for optimum speed and power
- Available in standard Pb-free and non Pb-free 32-lead (450-mil) SOIC and 32-lead TSOP II packages

## Functional Description

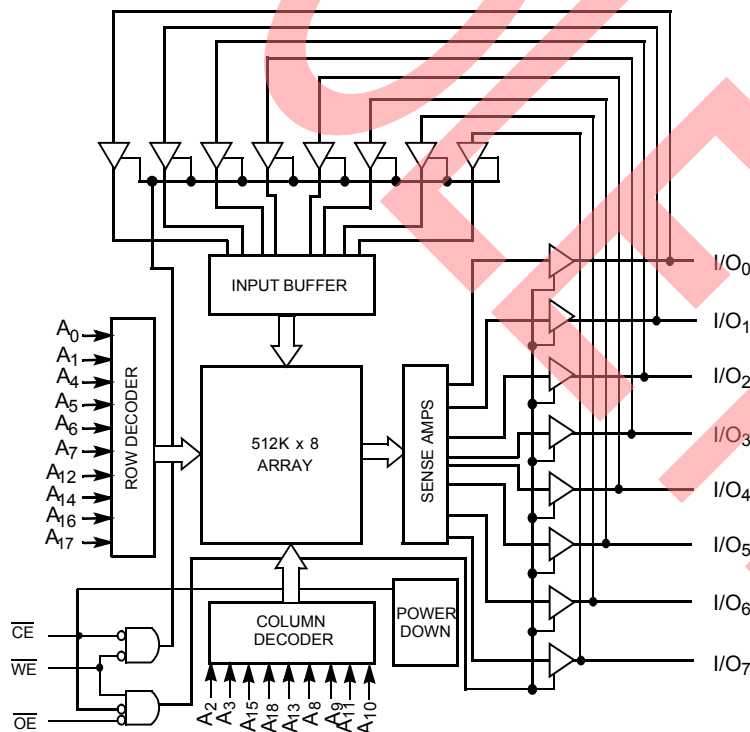
The CY62148BN is a high performance CMOS static RAM organized as 512K words by 8 bits. Easy memory expansion is provided by an active LOW Chip Enable ( $\overline{CE}$ ), an active LOW Output Enable ( $\overline{OE}$ ), and tri-state drivers. This device has an automatic power down feature that reduces power consumption by more than 99% when deselected.

To write to the device, take Chip Enable ( $\overline{CE}$ ) and Write Enable ( $\overline{WE}$ ) inputs LOW. Data on the eight I/O pins (I/O<sub>0</sub> through I/O<sub>7</sub>) is then written into the location specified on the address pins (A<sub>0</sub> through A<sub>17</sub>).

To read from the device, take Chip Enable ( $\overline{CE}$ ) and Output Enable ( $\overline{OE}$ ) LOW while forcing Write Enable ( $\overline{WE}$ ) HIGH for read. Under these conditions, the contents of the memory location specified by the address pins appear on the I/O pins.

The eight input/output pins (I/O<sub>0</sub> through I/O<sub>7</sub>) go into a high-impedance state when the device is deselected ( $\overline{CE}$  HIGH), the outputs are disabled ( $\overline{OE}$  HIGH), or a write operation is in progress ( $\overline{CE}$  LOW and  $\overline{WE}$  LOW).

## Logic Block Diagram

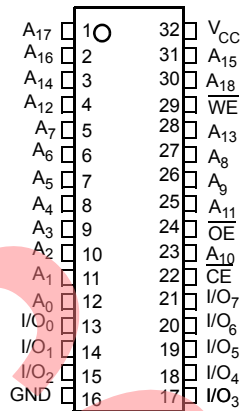


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## Pin Configuration

Top View  
SOIC  
TSOP II



## Product Portfolio

Product	V <sub>CC</sub> Range			Speed	Power Dissipation			
					Operating I <sub>CC</sub> (mA)		Standby I <sub>SB2</sub> (μA)	
	Min	Typ	Max		f = f <sub>max</sub>		Typ <sup>[1]</sup>	Max
			Typ <sup>[1]</sup>	Max				
CY62148BNLL	4.5 V	5.0V	5.5V	70 ns	12.5	20	4	20

### Note

1. Typical values are measured at V<sub>CC</sub> = 5V, T<sub>A</sub> = 25°C, and are included for reference only and are not tested or guaranteed.

## Maximum Ratings

Exceeding the maximum rating may impair the device's useful life. User guidelines only and are not tested.

Storage Temperature .....	-65°C to +150°C
Ambient Temperature with Power Applied .....	-55°C to +125°C
Supply Voltage on V <sub>CC</sub> to Relative GND .....	-0.5V to +7.0V
DC Voltage Applied to Outputs in High Z State <sup>[2]</sup> .....	-0.5V to V <sub>CC</sub> +0.5V

DC Input Voltage <sup>[2]</sup> .....	-0.5V to V <sub>CC</sub> +0.5V
Current into Outputs (LOW) .....	20 mA
Static Discharge Voltage .....	2001V (per MIL-STD-883, Method 3015)
Latch Up Current .....	>200 mA

## Operating Range

Range	Ambient Temperature <sup>[3]</sup>	V <sub>CC</sub>
Industrial	-40°C to +85°C	4.5V-5.5V

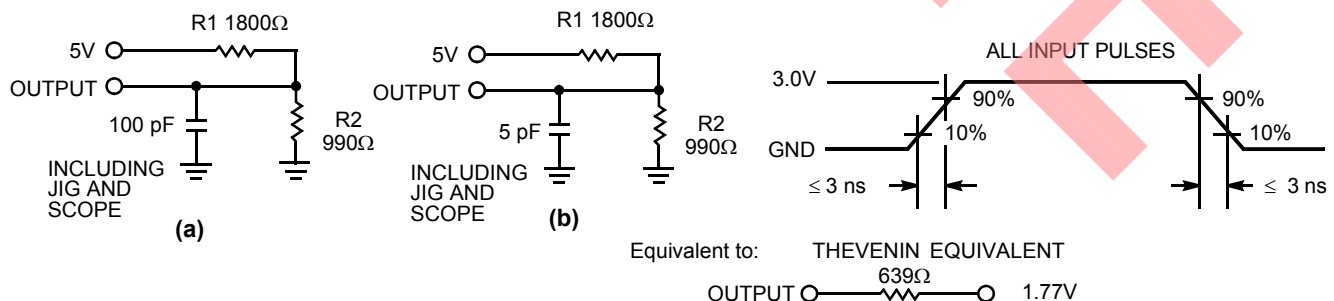
## Electrical Characteristics Over the Operating Range

Parameter	Description	Test Conditions	CY62148BN			Unit
			Min	Typ <sup>[1]</sup>	Max	
V <sub>OH</sub>	Output HIGH Voltage	I <sub>OH</sub> = -1 mA	2.4			V
V <sub>OL</sub>	Output LOW Voltage	I <sub>OL</sub> = 2.1 mA			0.4	V
V <sub>IH</sub>	Input HIGH Voltage		2.2		V <sub>CC</sub> +0.3	V
V <sub>IL</sub>	Input LOW Voltage		-0.3		0.8	V
I <sub>IX</sub>	Input Leakage Current	GND ≤ V <sub>I</sub> ≤ V <sub>CC</sub>	-1		+1	μA
I <sub>OZ</sub>	Output Leakage Current	GND ≤ V <sub>I</sub> ≤ V <sub>CC</sub> , Output Disabled	-1		+1	μA
I <sub>CC</sub>	V <sub>CC</sub> Operating Supply Current	f = f <sub>MAX</sub> = 1/t <sub>RC</sub>		12.5	20	mA
		f = 1 MHz	I <sub>OUT</sub> = 0 mA V <sub>CC</sub> = Max.,	2.5		mA
I <sub>SB1</sub>	Automatic CE Power Down Current – TTL Inputs	Max. V <sub>CC</sub> , CE ≥ V <sub>IH</sub> V <sub>IN</sub> ≥ V <sub>IH</sub> or V <sub>IN</sub> ≤ V <sub>IL</sub> , f = f <sub>MAX</sub>			1.5	mA
I <sub>SB2</sub>	Automatic CE Power Down Current – CMOS Inputs	Max. V <sub>CC</sub> , CE ≥ V <sub>CC</sub> - 0.3V, V <sub>IN</sub> ≥ V <sub>CC</sub> - 0.3V, or V <sub>IN</sub> ≤ 0.3V, f = 0	4		20	μA

## Capacitance<sup>[4]</sup>

Parameter	Description	Test Conditions	Max.	Unit
C <sub>IN</sub>	Input Capacitance	T <sub>A</sub> = 25°C, f = 1 MHz, V <sub>CC</sub> = 5.0V	6	pF
C <sub>OUT</sub>	Output Capacitance		8	pF

## AC Test Loads and Waveforms



### Notes

- V<sub>IL</sub> (min.) = -2.0V for pulse durations of less than 20 ns.
- T<sub>A</sub> is the "instant on" case temperature
- Tested initially and after any design or process changes that may affect these parameters.

**Switching Characteristics<sup>[5]</sup>** Over the Operating Range

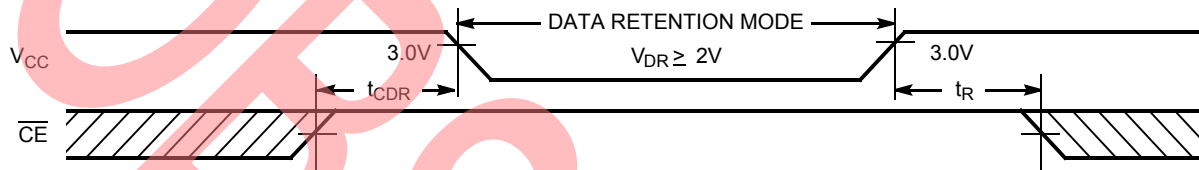
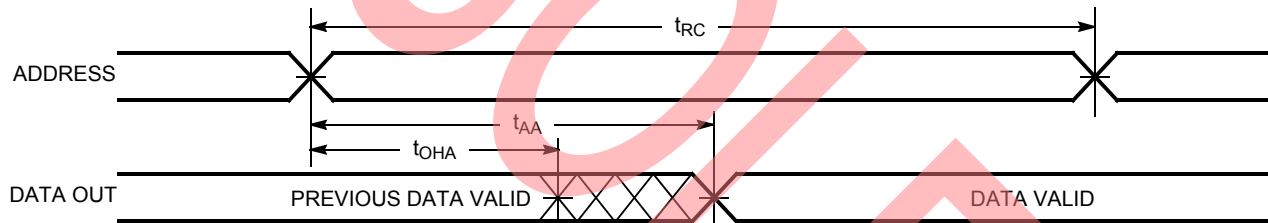
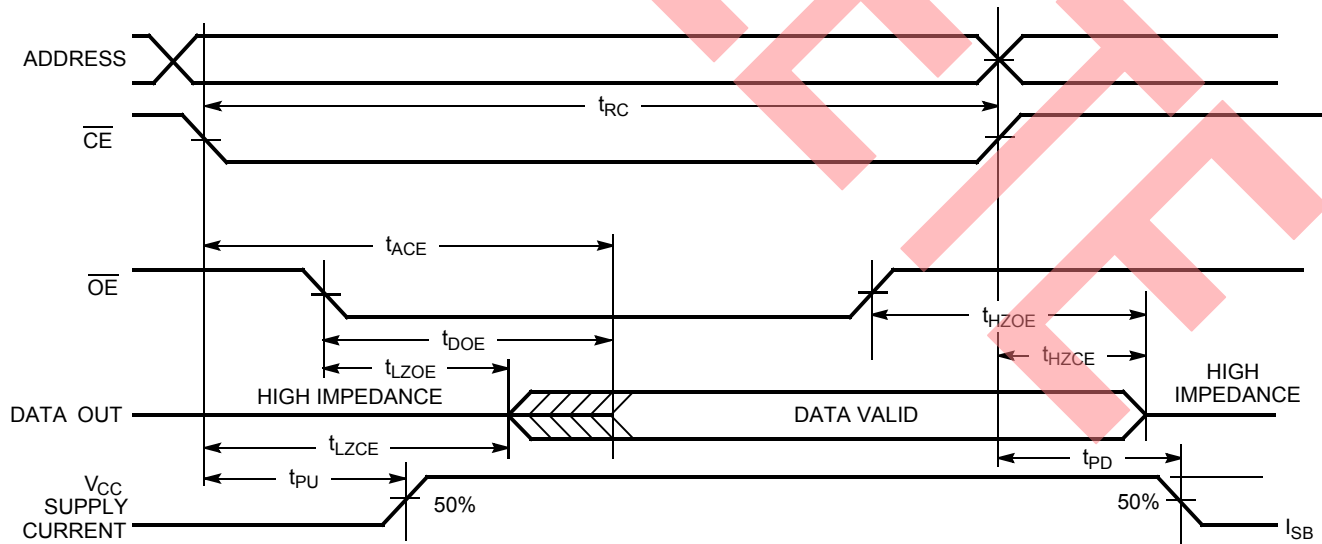
Parameter	Description	CY62148BN		Unit
		Min	Max	
<b>READ CYCLE</b>				
$t_{RC}$	Read Cycle Time	70		ns
$t_{AA}$	Address to Data Valid		70	ns
$t_{OHA}$	Data Hold from Address Change	10		ns
$t_{ACE}$	$\overline{CE}$ LOW to Data Valid		70	ns
$t_{DOE}$	$\overline{OE}$ LOW to Data Valid		35	ns
$t_{LZOE}$	$\overline{OE}$ LOW to Low Z <sup>[6]</sup>	5		ns
$t_{HZOE}$	$\overline{OE}$ HIGH to High Z <sup>[6, 7]</sup>		25	ns
$t_{LZCE}$	$\overline{CE}$ LOW to Low Z <sup>[6]</sup>	10		ns
$t_{HZCE}$	$\overline{CE}$ HIGH to High Z <sup>[6, 7]</sup>		25	ns
$t_{PU}$	$\overline{CE}$ LOW to Power Up	0		ns
$t_{PD}$	$\overline{CE}$ HIGH to Power Down		70	ns
<b>WRITE CYCLE<sup>[8]</sup></b>				
$t_{WC}$	Write Cycle Time	70		ns
$t_{SCE}$	$\overline{CE}$ LOW to Write End	60		ns
$t_{AW}$	Address Setup to Write End	60		ns
$t_{HA}$	Address Hold from Write End	0		ns
$t_{SA}$	Address Setup to Write Start	0		ns
$t_{PWE}$	$\overline{WE}$ Pulse Width	55		ns
$t_{SD}$	Data Setup to Write End	30		ns
$t_{HD}$	Data Hold from Write End	0		ns
$t_{LZWE}$	$\overline{WE}$ HIGH to Low Z <sup>[6]</sup>	5		ns
$t_{HZWE}$	$\overline{WE}$ LOW to High Z <sup>[6, 7]</sup>		25	ns

**Notes**

5. Test conditions assume signal transition time of 5 ns or less, timing reference levels of 1.5V, input pulse levels of 0 to 3.0V, and output loading of the specified  $I_{OL}/I_{OH}$  and 100-pF load capacitance.
6. At any given temperature and voltage condition,  $t_{HZCE}$  is less than  $t_{LZCE}$ ,  $t_{HZOE}$  is less than  $t_{LZOE}$ , and  $t_{HZWE}$  is less than  $t_{LZWE}$  for any given device.
7.  $t_{HZOE}$ ,  $t_{HZCE}$ , and  $t_{HZWE}$  are specified with a load capacitance of 5 pF as in part (b) of AC Test Loads. Transition is measured  $\pm 500$  mV from steady-state voltage.
8. The internal write time of the memory is defined by the overlap of  $\overline{CE}$  LOW, and  $\overline{WE}$  LOW.  $\overline{CE}$  and  $\overline{WE}$  must be LOW to initiate a write, and the transition of any of these signals can terminate the write. The input data setup and hold timing should be referenced to the leading edge of the signal that terminates the write.

**Data Retention Characteristics** (Over the Operating Range)

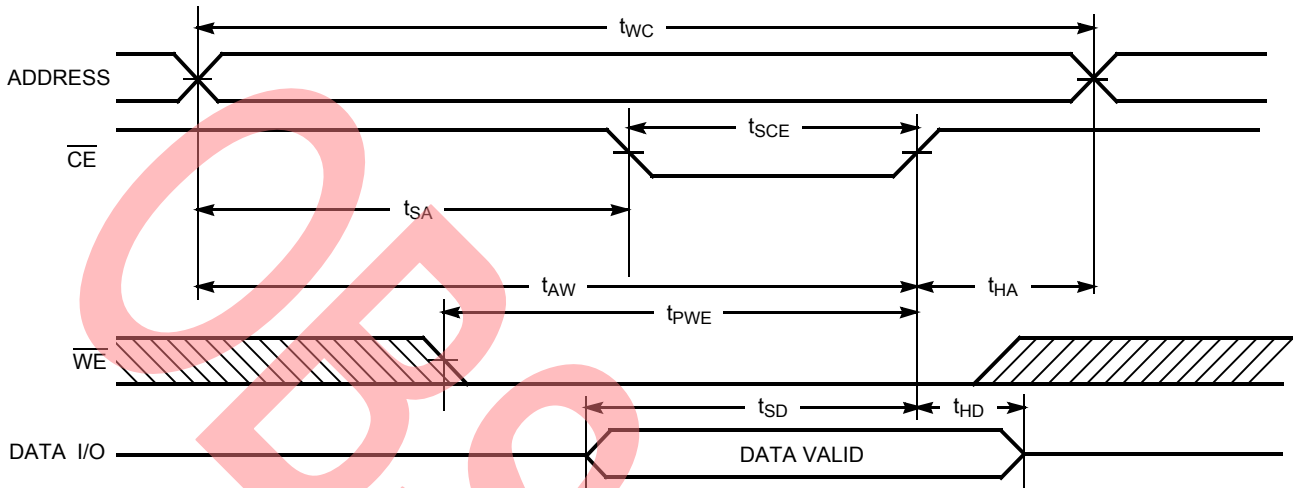
Parameter	Description	Conditions	Min	Typ <sup>[1]</sup>	Max	Unit
$V_{DR}$	$V_{CC}$ for Data Retention		2.0			V
$I_{CCDR}$	Data Retention Current	No input may exceed $V_{CC} + 0.3V$			20	$\mu A$
$t_{CDR}^{[4]}$	Chip Deselect to Data Retention Time	$V_{CC} = V_{DR}$ $CE > V_{CC} - 0.3V$	0			ns
$t_R^{[9]}$	Operation Recovery Time	$V_{IN} > V_{CC} - 0.3V$ or $V_{IN} < 0.3V$	$t_{RC}$			ns

**Data Retention Waveform**

**Switching Waveforms**
**Read Cycle No. 1<sup>[10, 11]</sup>**

**Read Cycle No. 2 ( $\overline{OE}$  Controlled)<sup>[11, 12]</sup>**

**Notes**

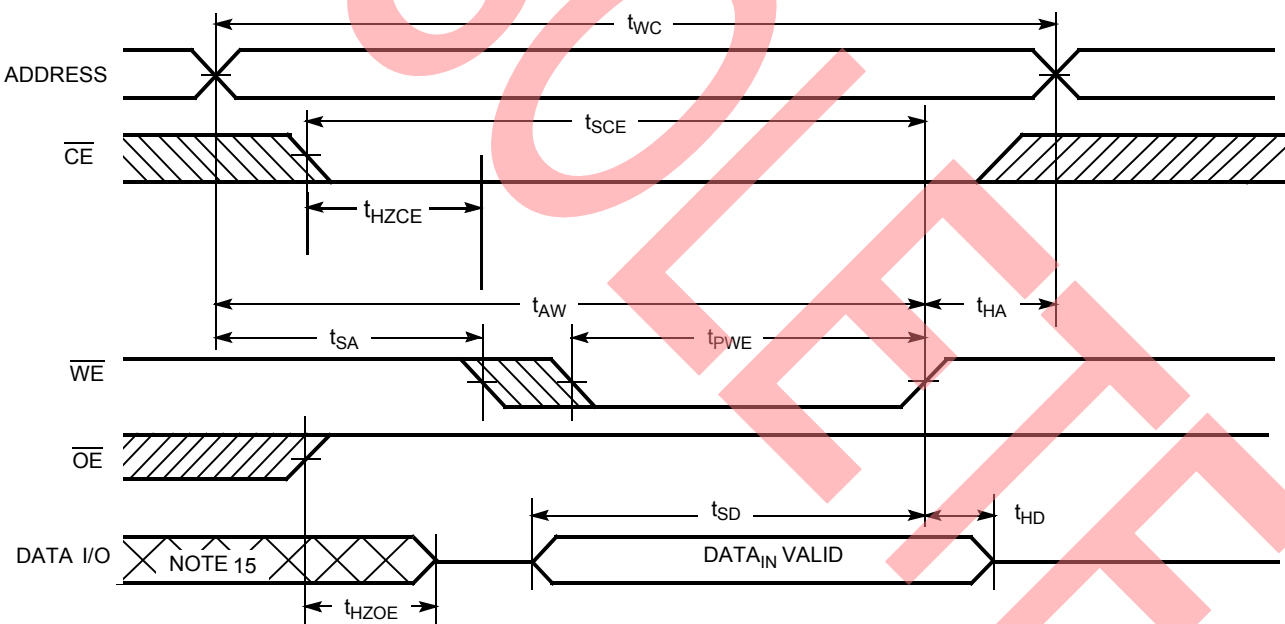
9. Full Device operation requires linear  $V_{CC}$  ramp from  $V_{DR}$  to  $V_{CC(min)} \geq 100$  ms or stable at  $V_{CC(min)} \geq 100$  ms.
10. Device is continuously selected.  $\overline{OE}, CE = V_{IL}$ .
11.  $\overline{WE}$  is HIGH for read cycle.
12. Address valid prior to or coincident with  $\overline{CE}$  transition LOW.

**Switching Waveforms** (continued)

**Write Cycle No. 1 ( $\overline{CE}$  Controlled)<sup>[13]</sup>**



**Write Cycle No. 2 ( $\overline{WE}$  Controlled,  $\overline{OE}$  HIGH During Write)<sup>[13, 14]</sup>**



**Notes**

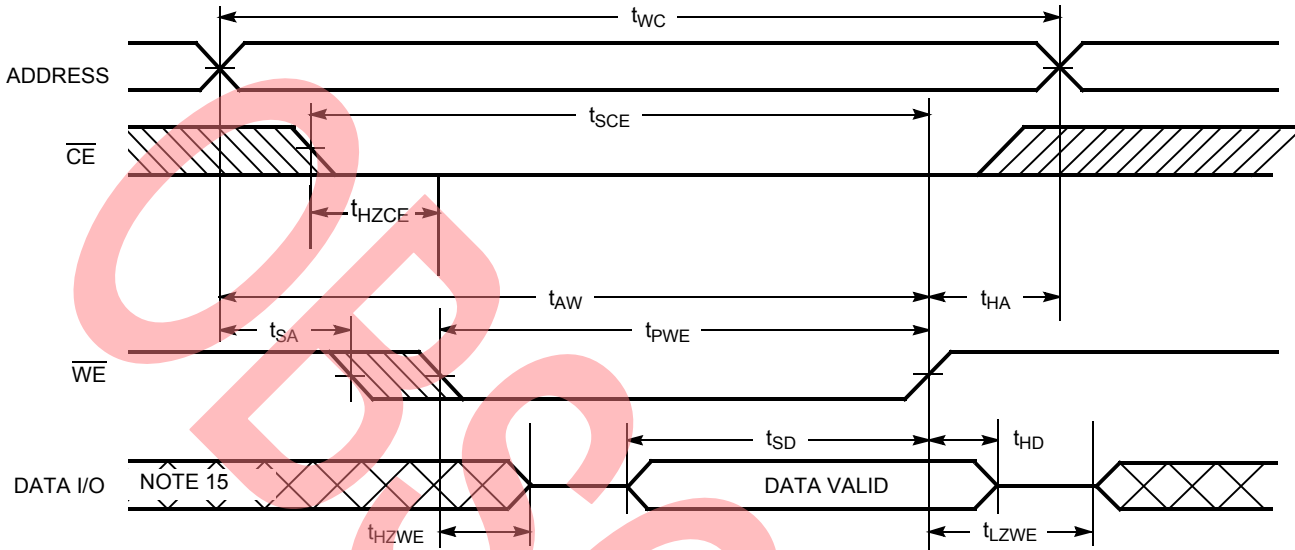
13. If  $\overline{CE}$  goes HIGH simultaneously with  $\overline{WE}$  going HIGH, the output remains in a high impedance state.

14. Data I/O is high-impedance if  $OE = V_{IH}$ .

15. During this period the I/Os are in the output state and input signals should not be applied.



**Switching Waveforms** (continued)

**Write Cycle No. 3 ( $\overline{WE}$  Controlled,  $\overline{OE}$  LOW)**<sup>[13, 14]</sup>

**Truth Table**

$\overline{CE}$	$\overline{OE}$	$\overline{WE}$	I/O <sub>0</sub> -I/O <sub>7</sub>	Mode	Power
H	X	X	High Z	Power Down	Standby ( $I_{SB}$ )
L	L	H	Data Out	Read	Active ( $I_{CC}$ )
L	X	L	Data In	Write	Active ( $I_{CC}$ )
L	H	H	High Z	Selected, Outputs Disabled	Active ( $I_{CC}$ )

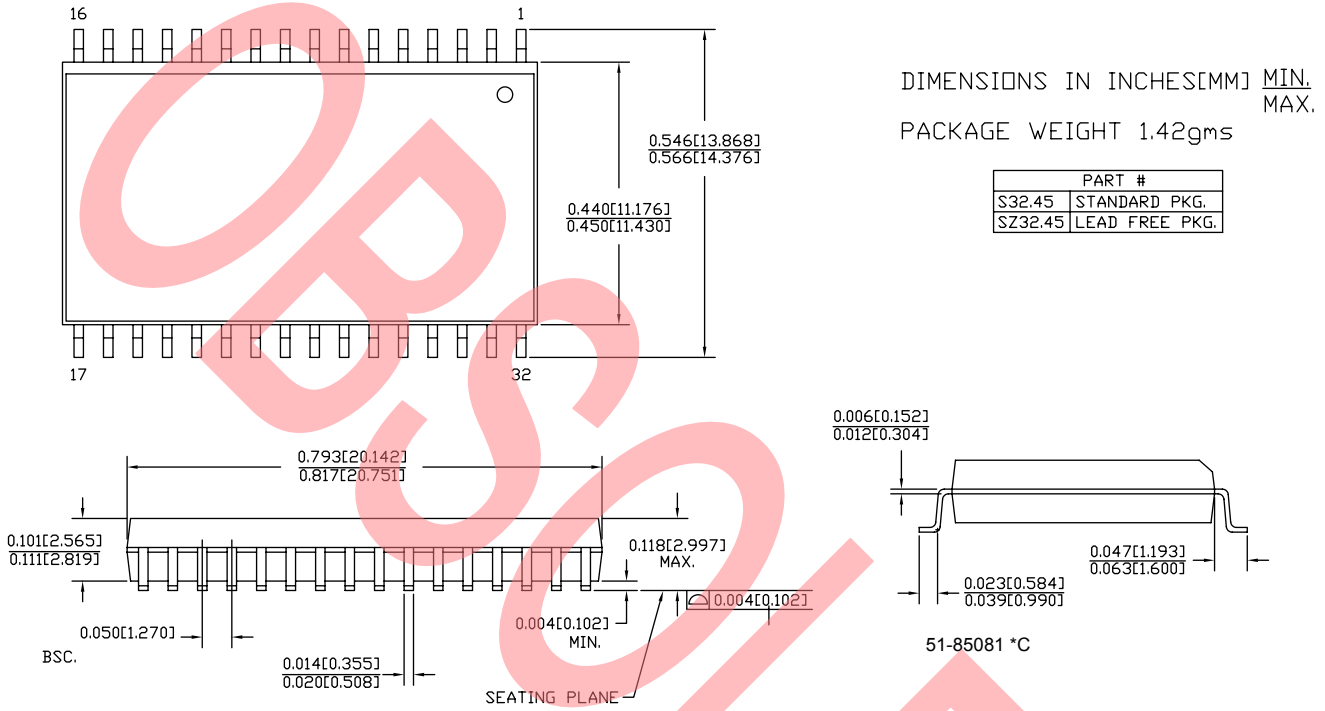
**Ordering Information**

Speed (ns)	Ordering Code	Package Diagram	Package Type	Operating Range
70	CY62148BNLL-70SX1	51-85081	32-lead (450-Mil) Molded SOIC (Pb-Free)	Industrial

Package Diagram

Figure 1. 32-lead (450 Mil) Molded SOIC (51-85081)

32 LD (450 Mil) SOIC



Document History Page

Document Title: CY62148BN MoBL® 4-Mbit (512K x 8) Static RAM Document Number: 001-06517				
REV.	ECN NO.	Issue Date	Orig. of Change	Description of Change
**	426504	See ECN	NXR	New Data Sheet
*A	485639	See ECN	VKN	Corrected the typo in the Array size in the Logic Block Diagram
*B	832320	See ECN	NXR	Removed Commercial Operating Range Removed 32-lead Reverse TSOP II package from product offering Corrected the test condition typo error in Electrical Characteristics table Updated Ordering information table
*C	2896152	03/18/2010	AJU	Removed inactive parts from Ordering Information. Added Table of Contents. Updated Packaging Information Updated links in Sales, Solutions, and Legal Information.
*D	2946367	06/07/2010	FSU	Removed unavailable parts.
*E	3094203	11/24/2010	RAME	The specified parts in the ordering information table are being pruned. Obsolete datasheet.

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